

CORRECTION

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Correction: Impact of aluminium addition on the corrosion behaviour of Sn–1.0Ag–0.5Cu lead-free solder

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www.rsc.org/advancesCorrection for 'Impact of aluminium addition on the corrosion behaviour of Sn–1.0Ag–0.5Cu lead-free solder' by N. I. M. Nordin *et al.*, *RSC Adv.*, 2015, 5, 99058–99064.

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The Royal Society of Chemistry apologises for these errors and any consequent inconvenience to authors and readers.

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